

The PE4134 is a high linearity, passive Quad MOSFET Mixer

+20 dBm. This mixer integrates passive matching networks to

range performance over a broad LO drive range of up to

provide single-ended interfaces for the RF and LO ports,

eliminating the need for external RF baluns or matching

down-conversion using low-side LO injection for PCS & 3G

The PE4134 is manufactured on Peregrine's UltraCMOS[™] process, a patented variation of silicon-on-insulator (SOI)

technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional

networks. The PE4134 is optimized for frequency

Base Station applications, and is also suitable for

for PCS & 3G Base Station Receivers, exhibiting high dynamic

Product Description

Product Specification

PE4134

High Linearity Quad MOSFET Mixer for PCS & 3G BTS

Features

- Integrated, single-ended RF & LO interfaces
- High linearity: IIP3 >+31 dBm, 1.9 GHz (+17 dBm LO)
- Low-conversion loss: 7.4 dB (+17 dBm LO)
- High isolation: Typical LO-IF at 33 dB, LO-RF at 31 dB
- Optimized for low-side LO injection
- Packaged in a 6-lead 3x3 mm DFN

Figure 1. Functional Diagram

CMOS.

up-conversion applications.

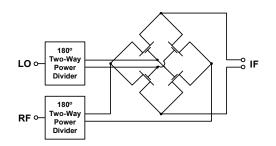


Table 1. AC and DC Electrical Specifications @ +25 °C

Minimum Parameter Typical Maximum Units Frequency Range: LO 1540 1740 MHz ---RF 1800 2000 MHz IF¹ 260 MHz Conversion Loss² 7.4 8.0 dB Isolation: LO-RF 27 31 dB LO-IF dB 27 33 Input IP3 1.8 GHz 26 29 dBm 31 1.9 GHz 33 dBm 2.0 GHz 28 31 dBm Input 1 dB Compression 22 dBm

Notes: 1. An IF frequency of 260 MHz is a nominal frequency. The IF frequency can be specified by the user as long as the RF and LO frequencies are within the specified maximum and minimum.

2. Conversion Loss includes loss of IF transformer (M/A COM ETK4-2T, nominal loss 0.7 dB at 260 MHz).

*Test conditions unless otherwise noted: IF = 260 MHz, LO input drive = 17 dBm, RF input drive = 3 dBm.



Figure 2. Package Type

6-lead 3x3 mm DFN



Figure 3. Pin Configuration (Top View)

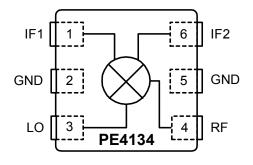


Table 2. Pin Descriptions

| Pin No. | Pin Name | Description |
|------------|-------------|---|
| 1 | IF1 | IF differential output |
| 2 | GND | Ground connections for Mixer. Traces should be physically short and connect immediately to ground plane for best performance. The exposed solder pad must also be soldered to the ground plane for best performance. |
| 3 | LO | LO Input |
| 4 | RF | RF Input |
| 5 | GND | Ground connections for Mixer. Traces should be physically short and connect immediately to ground plane for best performance. The exposed solder pad must also be soldered to the ground plane for best performance. |
| 6 | IF2 | IF differential output |

| Symbol | Parameter/Conditions | Min | Max | Units |
|------------------|-----------------------------|-----|-----|-------|
| T _{ST} | Storage temperature range | -65 | 150 | °C |
| T _{OP} | Operating temperature range | -40 | 85 | °C |
| P _{LO} | LO input power | | 20 | dBm |
| P _{RF} | RF input power | | 12 | dBm |
| V_{ESD} | ESD Sensitive Device | | 250 | V |

Table 3. Absolute Maximum Ratings

Absolute Maximum Ratings are those values listed in the above table. Exceeding these values may cause permanent device damage. Functional operation should be restricted to the limits in the DC Electrical Specifications table. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS[™] device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the rating specified.

Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS[™] devices are immune to latch-up.



Evaluation Kit

Figure 4. Evaluation Board Layout

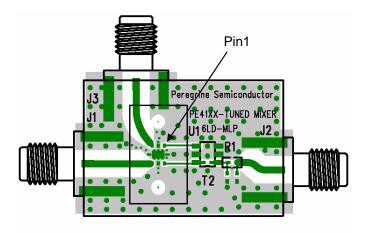


Figure 5. Evaluation Board Schematic Diagram

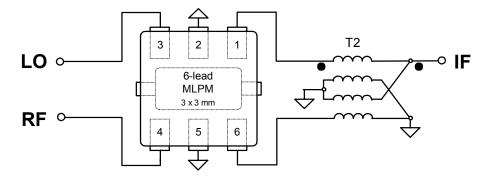
Table 4. Bill of Materials

| Reference | Value / Description | | |
|------------|---------------------|--|--|
| T2 | M/A Com ETK4-2T | | |
| R1 | 0 Ω | | |
| U1 | PE4134 MLP Mixer | | |
| J1, J2, J3 | SMA Connector | | |

Applications Support

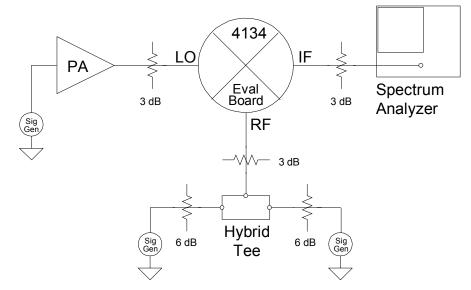
If you have a problem with your evaluation kit or if you have applications questions, please contact applications support:

E-Mail: help@psemi.com (fastest response) Phone: (858) 731-9400



T2, M/A-Com E-Series RF 4:1 Transformer, 2.0 - 1000 MHz, ETK4-2T

Figure 6. Evaluation Board Testing Block Diagram, 2-Tone Setup





Typical Performance Data (LO=17 dBm, RF=3 dBm, IF=260 MHz)

Figure 7. Conversion Loss

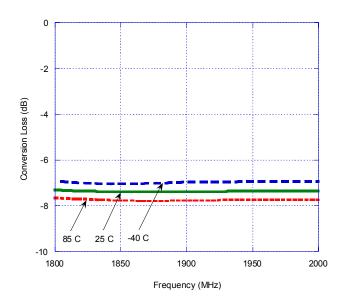


Figure 8. Input 1dB Compression

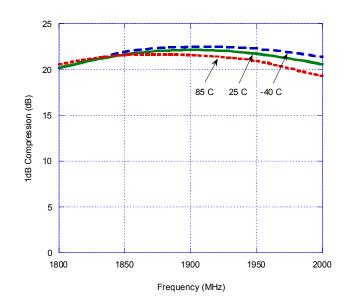


Figure 9. Input IP3

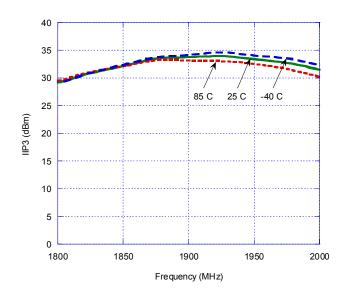
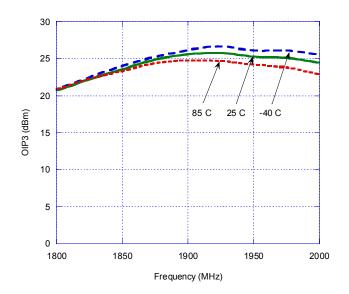


Figure 10. Output IP3

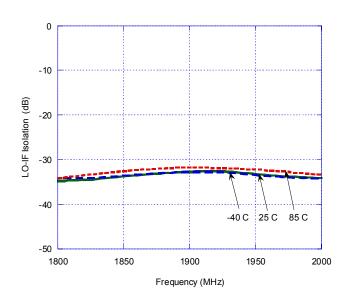




Typical Performance Data (LO=17 dBm, RF=3 dBm, IF=260 MHz)

Figure 11. LO-IF Isolation vs. Frequency

Figure 12. LO-RF Isolation vs. Frequency



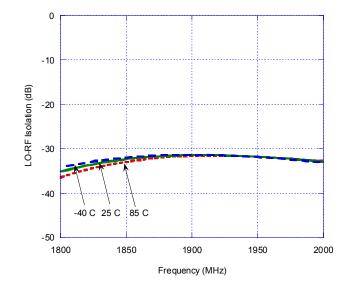


Figure 13. LO Port Return Loss @ 25°C

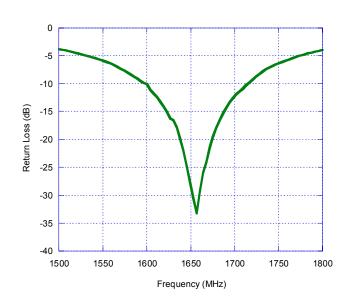
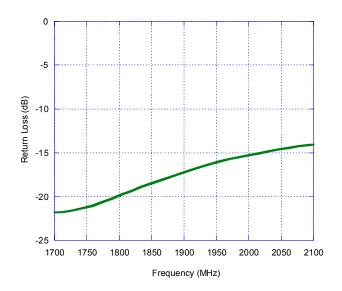


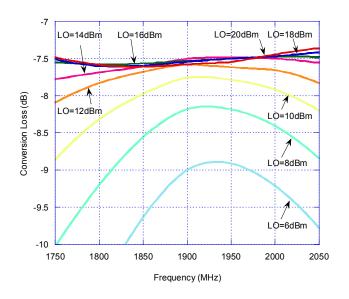
Figure 14. RF Port Return Loss @ 25°C





Typical Performance Data @ +25 °C (RF=3 dBm, IF=260 MHz)

Figure 15. Conversion Loss across LO Power



40 LO=20dBm 35 LO=18dBm LO=16dBm 30 LO=14dBm Input IP3 (dBm) LO=12dBm 25 LO=10dBm LO=8dBm 20 LO=6dBm 15 10 1750 1800 1850 1900 1950 2000 2050 Frequency (MHz)

Figure 16. Input IP3 across LO Power

Table 6. Spurious Response

| Spurious Response | | | | | |
|-------------------|---------|-----|-----|----|--|
| | mRF+nLO | | | | |
| | nLO | | | | |
| mRF | 1 | 2 | 3 | 4 | |
| 1 | 0 | 32 | 22 | 43 | |
| 2 | 57 | 49 | 61 | 62 | |
| 3 | 64 | 71 | 64 | 65 | |
| 4 | >85 | >85 | >85 | 81 | |

Normalized to dB below PIF

(RF=1900 Mhz @ 3 dBm, LO=1640 MHz @ 17 dBm)

Table 5. Spurious Response

| Spurious Response | | | | | |
|-------------------|-----|---------|-----|-----|--|
| | | mRF+nLO | | | |
| | nLO | | | | |
| mRF | 1 | 2 | 3 | 4 | |
| 1 | 5 | 37 | 30 | 50 | |
| 2 | 49 | 55 | 65 | 59 | |
| 3 | 75 | >85 | 78 | 80 | |
| 4 | >85 | 84 | >85 | >85 | |

Normalized to dB below PIF

(RF=1900 Mhz @ 3 dBm, LO=1640 MHz @ 17 dBm)



Figure 17. Package Drawing

6-lead DFN

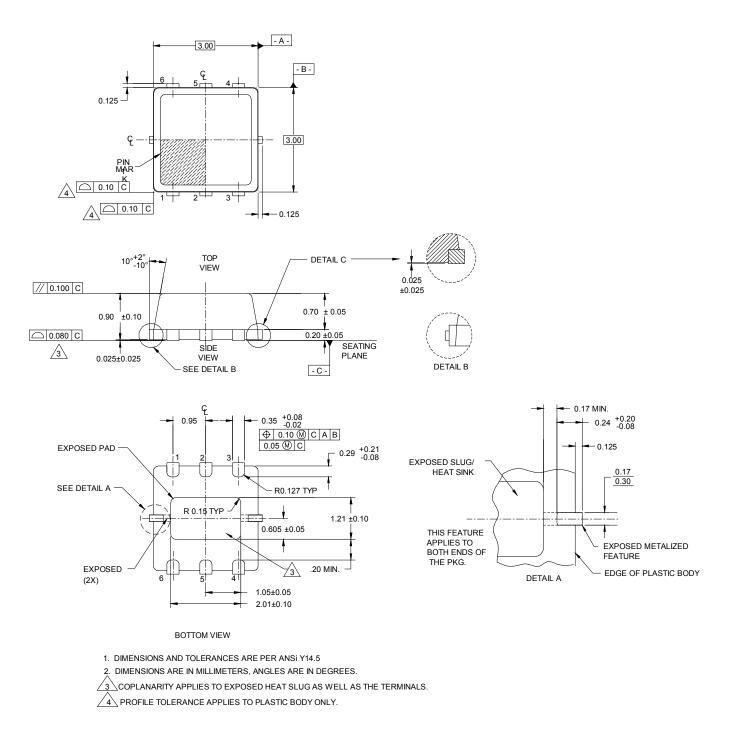




Figure 18. Tape and Reel Specifications

6-lead DFN

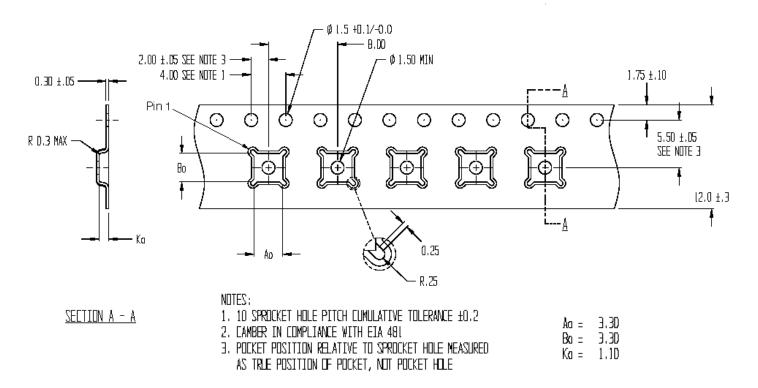


Table 7. Dimensions

| Dimension | DFN 3x3 mm | |
|--------------|--------------|--|
| Ao | 3.23 ± 0.1 | |
| Во | 3.17 ± 0.1 | |
| Ko | 1.37 ± 0.1 | |
| Р | 4 ± 0.1 | |
| W | 8 +0.3, -0.1 | |
| Т | 0.254 ± 0.02 | |
| R7 Quantity | 3000 | |
| R13 Quantity | N.A. | |

Note: R7 = 7 inch Lock Reel, R13 = 13 inch Lock Reel

Table 8. Ordering Information

| Order Code | Part Marking | Description | Package | Shipping Method |
|------------|--------------|------------------------|-------------------|------------------------|
| 4134-01 | 4134 | PE4134-06DFN3x3-12800F | 6-lead 3x3 mm DFN | 12800 units / Canister |
| 4134-02 | 4134 | PE4134-06DFN3x3-3000C | 6-lead 3x3 mm DFN | 3000 units / T&R |
| 4134-00 | 4134-EK | PE4134-06DFN3x3-EK | Evaluation Board | 1 / Box |

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Data Sheet Identification

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The product is in a formative or design stage. The data sheet contains design target specifications for product development. Specifications and features may change in any manner without notice.

Preliminary Specification

The data sheet contains preliminary data. Additional data may be added at a later date. Peregrine reserves the right to change specifications at any time without notice in order to supply the best possible product.

Product Specification

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